



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 16438C

Generic Copy

Issue Date: 13 Apr 2010

TITLE: Additional assembly site qualification for 20553-001 SOIC 16L device.

PROPOSED FIRST SHIP DATE: 13 Jul 2010

AFFECTED CHANGE CATEGORY(S): Assembly Manufacturing

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <Henry.Hernandez@onsemi.com>

SAMPLES:

Contact your local ON Semiconductor Sales Office or <Isa.Calderon@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or <Mark.Wasilewski@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

- Due to SOIC assembly capacity, ON Semiconductor has qualified an additional assembly site. This additional assembly site is ASECL, Taiwan. Products from ASECL are already qualified using halide-free mold compound.



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RELIABILITY DATA SUMMARY:

Reliability qualification has been successfully completed with the below data summary:

Test	Results
External Visual	0/462
MSL2 Preconditioning	0/462
Temperature Cycle, 500 Cy, -65C to +150C	0/231
Unbiased HAST, 192 Hrs, 130C, 85%RH	0/231
High Temperature Bake, 1000 Hrs, 150C	0/77
Solderability	Pass
Wire Pull	Pass
Ball Shear	Pass
Physical Dimension	Pass
Marking Permanency	Pass